



深圳康比电子有限公司

KANGBI TECHNOLOGY INDUSTRY CO.,LTD.

产品规格书

SAMPLE APPROVAL SHEET

CUSTOMER客户:	_____
SIZE UP规格:	<u>SMD-3030mm</u>
MODEL型号:	<u>R315M</u>
NUMBER数量:	_____
DATE日期:	_____

Customer’s Approval Certificate

Please return this copy as a certification of
Y our approval

Checked & Approval by:

Date:

SAW RESONATOR

KB315M SMD-3030mm

This specification shall cover the characteristics of 1-port SAW resonator with R315M used for remote-control security.

2. Electrical Specification

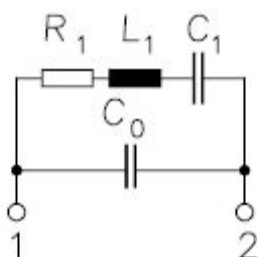
2.1 Maximum Rating

DC Voltage VDC	10V
AC Voltage Vpp	10V 50Hz/60Hz
Operation temperature	-40℃ to +85℃
Storage temperature	-45℃ to +85℃
Source Power	0dBm

2.2 Electronic Characteristics

Item		Unites	Minimum	Typical	Maximum
Center Frequency		MHz	314.925	315.000	315.075
Insertion Loss		dB		1.4	1.9
Quality Factor	Unload Q		8000	12800	
	50Ω Loaded Q		1000	2000	
Temperature	Turnover Temperature	℃	10	25	40
Stability	Freq.temp.Coefficient	ppm/℃		0.032	
Frequency Aging		ppm/yr		<±10	
DC. Insulation Resistance		MΩ	1.0		
RF Equivalent RLC Model	Motional Resistance R1	Ω		17.6	
	Motional Inductance L1	μH		118	
	Motional Capacitance C1	fF		2.16	
Transducer Static Capacitance C0		pF		2.13	

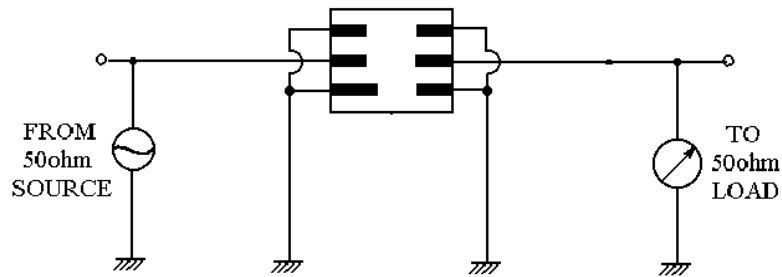
2.3 Equivalent LC Model



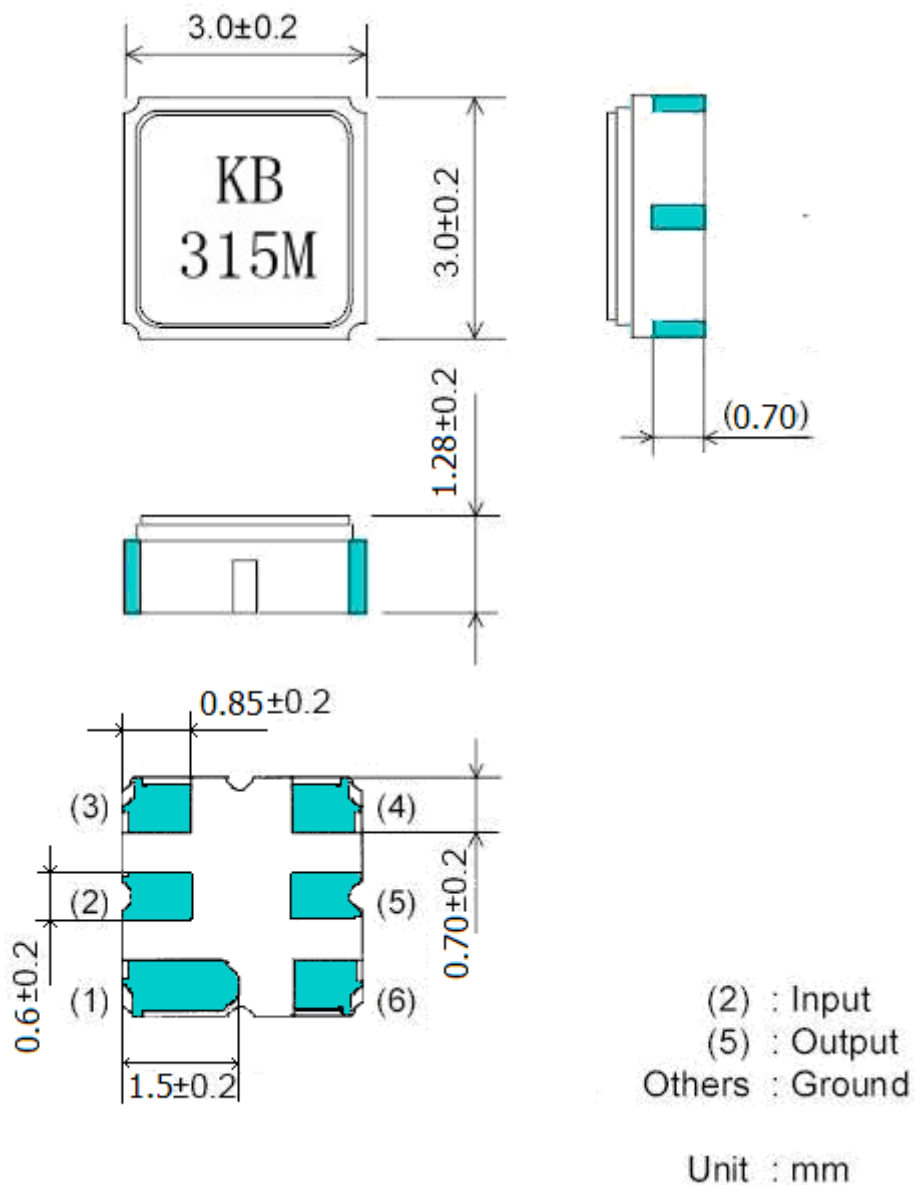
3. Test Circuit

SAW RESONATOR

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4. Dimension



1. KB: Manufacture's logo
2. R315M : Model code

5. Environment Characteristic

5-1 Thermal Shock:

The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: $T_A = -40^{\circ}\text{C} \pm 3^{\circ}\text{C}$, $T_B = 85^{\circ}\text{C} \pm 2^{\circ}\text{C}$, $t_1 = t_2 = 30\text{min}$, switch time $\leq 3\text{min}$ & cycle time : 100 times, recovery time: $2\text{h} \pm 0.5\text{h}$.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

5-3 Solder ability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2

5-4 The Temperature Storage:

5.3.1 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for $96\text{h} \pm 4\text{h}$, recovery time : $2\text{h} \pm 0.5\text{h}$.

5.3.2 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the $-40^{\circ}\text{C} \pm 3^{\circ}\text{C}$ for $96\text{h} \pm 4\text{h}$, recovery time : $2\text{h} \pm 0.5\text{h}$.

5-5 Humidity test:

The components shall remain within the electrical specifications after being kept at the condition of ambient temperature $60^{\circ}\text{C} \pm 2^{\circ}\text{C}$, and 90~96% RH for $96\text{h} \pm 4\text{h}$.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m for 3 times. The resonator shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 2 hour each in X, Y and Z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The resonator shall fulfill the specifications in 2.2.

6. Remark

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

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7. Packing

(1) Carrier Tape: Figure 1

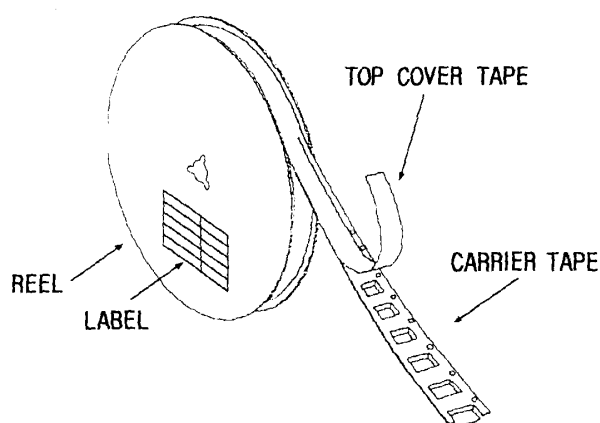
(2) Reel: Figure 2

(3) The product shall be packed properly not to be damaged during transportation and storage.

1000 pcs/reel 7"

3000 pcs/reel 13''

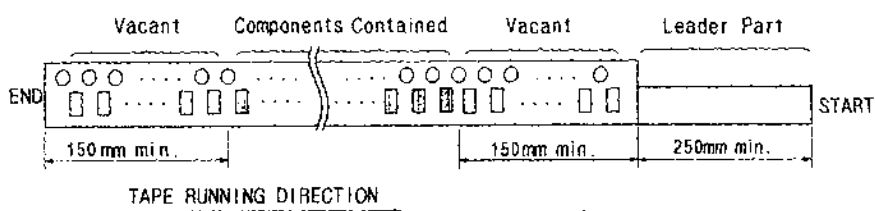
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.



8. Tape Specifications

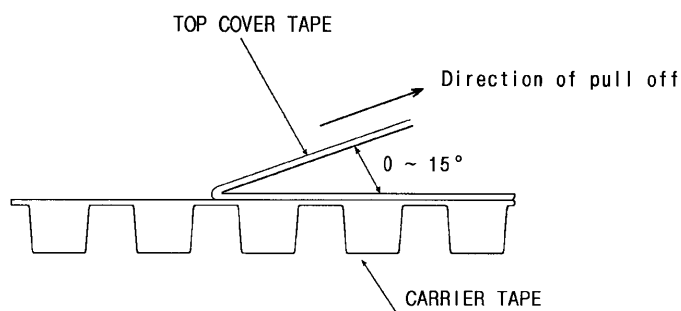
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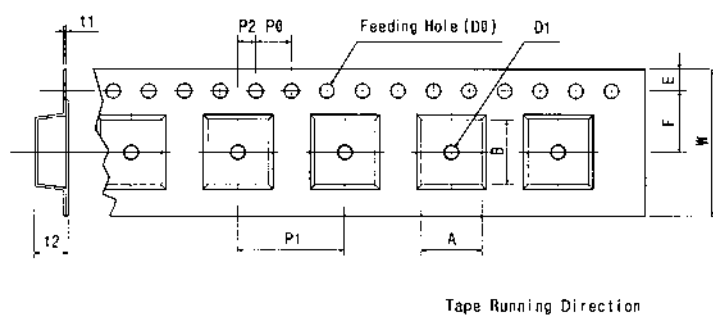
8.1 Tensile Strength of Carrier Tape: 4.4N/mm width

8.2 Top Cover Tape Adhesion (See the below figure)

- (1) pull off angle: $0 \sim 15^\circ$
- (2) speed: 300mm/min.
- (3) force: 20~70g



[Figure 1] Carrier Tape Dimensions



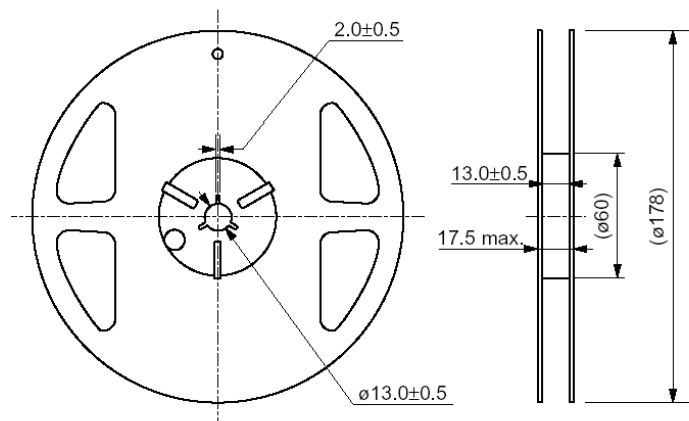
[Unit: mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.0	5.5	1.75	4.0	4.0	2.0	Ø1.5	Ø1.0	0.3	1.25	3.3±	3.3±
±0.3	±0.05	±0.1	±0.1	±0.1	±0.05	±0.1	±0.25	±0.05	±0.1	0.1	0.1

[Figure 2] Reel Dimensions

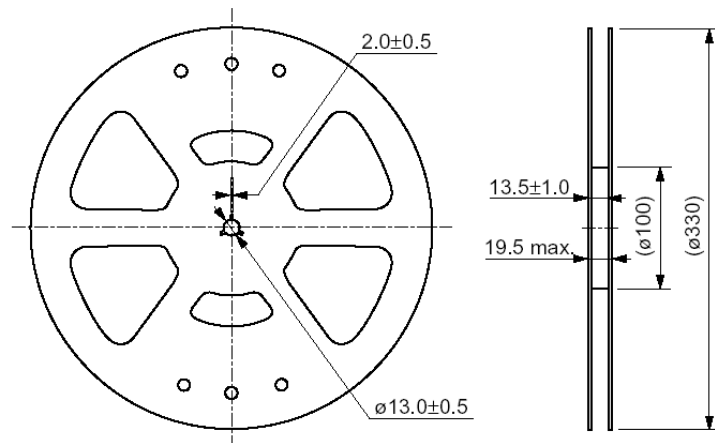
SAW RESONATOR

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ø178 Reel Dimension

(in mm)



ø330 Reel Dimension

(in mm)